

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>SATORU IDEGUCHI</td> <td>10/16/2013</td> </tr> <tr> <td>HIDEYO OSANAI</td> <td>10/16/2013</td> </tr> <tr> <td>HIROTAKA KOTANI</td> <td>10/17/2013</td> </tr> </tbody> </table>		Name	Execution Date	SATORU IDEGUCHI	10/16/2013	HIDEYO OSANAI	10/16/2013	HIROTAKA KOTANI	10/17/2013				
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<table border="1"> <tr> <td>Name:</td> <td>DOWA METALTECH CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>14-1, SOTOKANDA 4-CHOME,</td> </tr> <tr> <td>Internal Address:</td> <td>CHIYODA-KU</td> </tr> <tr> <td>City:</td> <td>TOKYO</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>101-8617</td> </tr> </table>		Name:	DOWA METALTECH CO., LTD.	Street Address:	14-1, SOTOKANDA 4-CHOME,	Internal Address:	CHIYODA-KU	City:	TOKYO	State/Country:	JAPAN	Postal Code:	101-8617
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CORRESPONDENCE DATA													
Fax Number:	(203)865-0297												
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Email:	docket@bachlap.com												
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>													
Correspondent Name:	BACHMAN & LAPOINTE, P.C.												
Address Line 1:	900 CHAPEL STREET												
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Address Line 4:	NEW HAVEN, CONNECTICUT 06510												
ATTORNEY DOCKET NUMBER:	13-350												
NAME OF SUBMITTER:	GREGORY P. LAPOINTE												

Signature:	/Gregory P. LaPointe/
Date:	10/31/2013
Total Attachments: 2 source=13-350_Executed_Assignment_10-31-13#page1.tif source=13-350_Executed_Assignment_10-31-13#page2.tif	

ASSIGNMENT

In consideration of One Dollar (\$1.00), and other good and valuable consideration, the receipt of which is hereby acknowledged, We, the undersigned, Satoru Ideguchi, a citizen of Japan and a resident of 202 Surplus Shibachaya, 2138-1, Hirookatakaide, Shiojiri-shi, Nagano 399-0703, Japan, Hideyo Osanai, a citizen of Japan and a resident of 2115-1-101, Hirookatakaide, Shiojiri-shi, Nagano 399-0703, Japan, and Hirotaka Kotani, a citizen of Japan and a resident of A102 Seiwayou, 2105-1, Hirookatakaide, Shiojiri-shi, Nagano 399-0703, Japan, hereby sell, assign and transfer to DOWA METALTECH CO., LTD., a corporation of Japan, having a place of business at 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 101-8617, Japan, its successors, assigns and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the following application for United States Letters Patent:

Serial No.: 14/036,551

Filing Date: September 25, 2013

Title: HEAT RADIATING PLATE AND METHOD FOR PRODUCING SAME

Inventors: Satoru Ideguchi et al.

Attorney's Docket No. 13-350

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said

improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

(L.S.) Satoru Ideguchi Oct. 16, 2013
Satoru Ideguchi (Date)

(L.S.) Hideyo Osanai Oct. 16, 2013
Hideyo Osanai (Date)

(L.S.) Hiroataka Kotani Oct. 17, 2013
Hiroataka Kotani (Date)